

NTC thermistors for temperature measurement

Probe assemblies, pipe mounted sensors

Series/Type: B58100

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B58100

T120

Temperature measurement	
Probe assemblies	

Applications

■ Pipe mounted sensor for temperature measurement of fluids in pipes

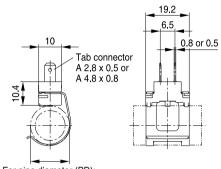
Features

- Short response time due to glass-encapsulated NTC thermistor
- Fast and easy mounting

Options

- Available for pipes with diameter 13.5, 15, 18, 19 and 22 mm
- Alternative resistance ratings available on request
- Alternative fast-on plug terminals 2.8 x 0.5 or 4.8 x 0.8 mm available

Dimensional drawing



For pipe diameter (PD): ø13.5, 15, 18, 19 and 22 mm

Dimensions in mm

TNT0461-C-E

Delivery mode

Bulk

General technical data

Climatic category	(IEC 60068-1)		5/100/21	
Maximum power	(at 25 °C)	P ₂₅	18	mW
Resistance tolerance		$\Delta R_R/R_R$	±3.6	%
Rated temperature		T_R	60	°C
Thermal time constant	(measured on pipe)	τ_{a}	< 5	s
Insulation resistance	(V = 100 V DC, t = 1 min)	R _{ins}	> 10	$M\Omega$
Dissipation factor	(in air)	δ_{th}	approx. 2.1	mW/K
Test voltage	(t = 1 s)	V_{test}	500	V AC

Electrical specification and ordering codes

R ₆₀	R ₂₅	No. of	B _{25/100}	B _{0/100}	for pipe	Ordering code
		R/T characteristic			diameter	
Ω	Ω		K	K	mm	
3000	10110	8407	3497	3450 ±1%	18/19	B58100A0506A000
3000	10110	8407	3497	3450 ±1%	13.5	B58100A0527A000
2500	10151	8317	4005 ±1%	3970	22	B58100A0439A000
2500	10151	8317	4005 ±1%	3970	15	B58100A0507A000
2500	10151	8317	4005 ±1%	3970	13.5	B58100A0628A000
2500	10151	8317	4005 ±1%	3970	18/19	B58100A0629A000



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Reliability data

Test	Standard	Test conditions	$\Delta R_{100}/R_{100}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2	Storage at upper category temperature T: 100 °C t: 500 h	< 3%	No visible damage
Storage in damp heat, steady state	IEC 60068-2-78	Temperature of air: 85 °C Relative humidity of air: 85% Duration: 21 days	< 5%	No visible damage
Rapid temperature cycling	IEC 60068-2-14	Lower test temperature: 5 °C Upper test temperature: 85 °C Number of cycles: 100	< 3%	No visible damage
Thermal overload		Short time overload: 125 °C t: 10 h	< 3%	No visible damage

Note

- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals).
- Avoid dewing and condensation unless thermistor is specified for these conditions.



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R/T characteristics

	8317		0407	
R/T No.	44.1		8407	
T (°C)	$B_{25/100} = 4005 \text{ K}$		$B_{0/100} = 3450 \text{ K}$	
	R _T /R ₂₅	α (%/K)	R _T /R ₂₅	α (%/K)
-55.0	99.49	7.4	51.991	6.4
-50.0	69.168	7.2	37.989	6.2
-45.0	48.679	6.9	28.07	5.9
-40.0	34.662	6.7	20.96	5.7
-35.0	24.959	6.5	15.809	5.5
-30.0	18.166	6.3	12.037	5.4
-25.0	13.358	6.1	9.2484	5.2
-20.0	9.9201	5.9	7.1668	5.0
-15.0	7.4369	5.7	5.5993	4.9
-10.0	5.6261	5.5	4.4087	4.7
-5.0	4.2935	5.3	3.4971	4.6
0.0	3.304	5.2	2.7936	4.4
5.0	2.5632	5.0	2.2468	4.3
10.0	2.0038	4.9	1.8187	4.2
15.0	1.5783	4.7	1.4813	4.0
20.0	1.252	4.6	1.2136	3.9
25.0	1.0000	4.4	1.0000	3.8
30.0	0.80403	4.3	0.82845	3.7
35.0	0.6506	4.2	0.68991	3.6
40.0	0.52967	4.1	0.57742	3.5
45.0	0.43377	3.9	0.4856	3.4
50.0	0.35726	3.8	0.41026	3.3
55.0	0.29585	3.7	0.34816	3.2
60.0	0.24629	3.6	0.29673	3.2
65.0	0.20608	3.5	0.25393	3.1
70.0	0.17327	3.4	0.21817	3.0
75.0	0.14638	3.3	0.18816	2.9
80.0	0.12422	3.2	0.16288	2.8
85.0	0.10588	3.2	0.1415	2.8
90.0	0.090628	3.1	0.12335	2.7
95.0	0.07789	3.0	0.10788	2.6
100.0	0.067207	2.9	0.094659	2.6

Cautions and warnings

General

See "Important notes" on page 2.

Storage

- Store thermistors only in original packaging. Do not open the package prior to processing.
- Storage conditions in original packaging: storage temperature −25 °C ... +45 °C, relative humidity ≤75% annual mean, <95% maximum 30 days per annum, dew precipitation is inadmissible.</p>
- Do not store thermistors where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or components may stick together, causing problems during mounting.
- Avoid contamination of thermistor surface during storage, handling and processing.
- Avoid storage of thermistors in harmful environments like corrosive gases (SO_x, Cl etc).
- Use the components as soon as possible after opening the original packaging.
- Solder thermistors within the time specified after shipment from EPCOS.
 For leaded components this is 24 months, for SMD components with nickel barrier termination 12 months, for leadless components this is 12 months, for SMD components with AgPd termination 6 months.

Handling

- NTC thermistors must not be dropped. Chip-offs or any other damage must not be caused during handling of NTCs.
- Do not touch components with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.

Mounting

- Ensure that no thermo-mechanical stress occurs due to production processes (curing or overmolding processes) when thermistors are sealed, potted or overmolded or during their subsequent operation. The maximum temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing/potting compound and plastic material) are chemically neutral.
- Electrodes/contacts must not be scratched or damaged before/during/after the mounting process.
- Contacts and housing used for assembly with the thermistor must be clean before mounting.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand the temperature.
- Avoid contamination of the thermistor surface during processing.
- The connections of sensors (e.g. cable end, wire end, plug terminal) may only be exposed to an environment with normal atmospheric conditions.
- Tensile forces on cables or leads must be avoided during mounting and operation.
- Bending or twisting of cables or leads directly on the thermistor body is not permissible.
- Avoid using chemical substances as mounting aids. It must be ensured that no water or other liquids enter the NTC thermistors (e.g. through plug terminals). In particular, water based substances (e.g. soap suds) must not be used as mounting aids for sensors.
- The use of no-clean solder products is recommended. In any case mild, non-activated fluxes should be used. Flux residues after soldering should be minimized.

Operation

- Use thermistors only within the specified operating temperature range.
- Use thermistors only within the specified power range.
- Environmental conditions must not harm the thermistors. Only use the thermistors under normal atmospheric conditions or within the specified conditions.
- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. perfluoropolyethers such as Galden).
- Avoid dewing and condensation unless thermistor is specified for these conditions.
- Bending or twisting of cables and/or wires is not permissible during operation of the sensor in the application.



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sheets, data books, other publications, on the EPCOS website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes



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Symbols and terms

Symbol	English	German
A AWG	Area American Wire Gauge	Fläche Amerikanische Norm für Drahtquerschnitte
B B _{25/100}	B value B value determined by resistance measurement at 25 °C and 100 °C	B-Wert B-Wert, ermittelt durch Widerstands- messungen bei 25 °C und 100 °C
C_{th}	Heat capacitance	Wärmekapazität
1	Current	Strom
$\begin{array}{l} N \\ P_{25} \\ P_{diss} \\ P_{el} \\ P_{max} \end{array}$	Number (integer) Maximum power at 25 °C Power dissipation Electrical power Maximum power within stated temperature range	Anzahl (ganzzahliger Wert) Maximale Leistung bei 25 °C Verlustleistung Elektrische Leistung Maximale Leistung im angegebenenTemperaturbereich
$\begin{array}{l} \Delta R_{\text{B}}/R_{\text{B}} \\ \\ R_{\text{ins}} \\ R_{\text{P}} \\ \\ R_{\text{R}} \\ \Delta R_{\text{R}}/R_{\text{R}} \\ \\ R_{\text{S}} \\ \\ R_{\text{T}} \end{array}$	Resistance tolerance caused by spread of B value Insulation resistance Parallel resistance Rated resistance Resistance tolerance Series resistance Resistance at temperature T (e.g. R ₂₅ = resistance at 25 °C)	Widerstandstoleranz, die durch die Streuung des B-Wertes verursacht wird Isolationswiderstand Parallelwiderstand Nennwiderstand Widerstandstoleranz Serienwiderstand Widerstand bei Temperatur T (z.B. R ₂₅ = Widerstand bei 25 °C)
$T \\ \Delta T \\ t \\ T_A \\ T_{max} \\ T_{min} \\ T_{op} \\ T_R \\ T_{surf}$	Temperature Temperature tolerance Time Ambient temperature Upper category temperature Lower category temperature Operating temperature Rated temperature Surface temperature	Temperatur Temperaturtoleranz Zeit Umgebungstemperatur Obere Grenztemperatur (Kategorietemperatur) Untere Grenztemperatur (Kategorietemperatur) Betriebstemperatur Nenntemperatur Oberflächentemperatur
V V _{ins} V _{op} V _{test}	Voltage Insulation test voltage Operating voltage Test voltage	Spannung Isolationsprüfspannung Betriebsspannung Prüfspannung



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Symbol	English	German
α	Temperature coefficient	Temperaturkoeffizient
Δ	Tolerance, change	Toleranz, Änderung
δ_{th}	Dissipation factor	Wärmeleitwert
$ au_c$ $ au_a$	Thermal cooling time constant Thermal time constant	Thermische Abkühlzeitkonstante Thermische Zeitkonstante

Abbreviations / Notes

Symbol	English	German
SMD	Surface-mounted devices	Oberflächenmontierbares Bauelement
*	To be replaced by a number in ordering codes, type designations etc.	Platzhalter für Zahl im Bestellnummern- code oder für die Typenbezeichnung.
+	To be replaced by a letter.	Platzhalter für einen Buchstaben.
	All dimensions are given in mm.	Alle Maße sind in mm angegeben.
	The commas used in numerical values denote decimal points.	Verwendete Kommas in Zahlenwerten bezeichnen Dezimalpunkte.



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